IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Date: July 6, 2006

Applicants: Bednorz et al.

Docket: YO987-074BZ

Serial No.: 08/479,810

Group Art Unit: 1751

Filed: June 7, 1995

Examiner: M. Kopec

For: NEW SUPERCONDUCTIVE COMPOUNDS HAVING HIGH TRANSITION

TEMPERATURE, METHODS FOR THEIR USE AND PREPARATION

Mail Stop: AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby-certify that this Fourth Response After Final Rejection, (3 Pages) is being facsimile transmitted to the U.S. Patent and Trademark Office to (571) 273-8300

on July 6, 2006

Dr. Daniel P. Morris, Esq.

Reg. No. 32,053

FOURTH RESPONSE AFTER FINAL REJECTION

Sir:

In response to the Final Office Action dated October 20, 2005, please consider the following:

In the Supplementary Amendment submitted August 24, 2000, applicants referred to the books listed below as Attachments C to G which were submitted in the parent application Serial No.: 08/303,561. In the Interview Summary dated 06/17/2005 the Examiner indicated that these books would be placed in the file of the present application. According to Craig Feinberg of the Office of the Board of Appeals and Interferences these books must appear in the formal record as "Artifacts" so that they can be referred to in the appeal brief which applicants will submit pursuant to the Notice of Appeal. Mr. Feinberg indicated that these books can be "Artifacts" in either the file of application Serial No.: 08/303,561 or the present file. Mr. Feinberg checked the electronic file for both applications. Neither application listed any artifacts. Mr. Feinberg requested applicant to bring this to the Examiner's attention so that the books listed below can be entered in the electronic file as "Artifacts."

1. Attachment C

Ginsburg, D.M., Ed., Physical Properties of High-Temperature Superconductors, Vols. I-III, World Scientific, Singapore, 1989-1992.

Attachment D

Rao, C.N.R., Ed., Chemistry of High-Temperature Superconductors, World Scientific, Singapore, 1991.

3. Attachment E

Shackelford, J.F., The CRC Materials Science and Engineering Handbook, CRC Press, Boca Raton, 1992, 98-99 and 122-123.

4. Attachment F

Kaldis, E., Ed., Materials and Crystallographic Aspects of HTc-Superconductivity, Kluwer Academic Publ., Dordrecht, The Netherlands, 1992.

5. Attachment G

Malik, S.K. and Shah, S.S., Ed., Physical and Material Properties of High Temperature Superconductors, Nova Science Publ., Commack, N.Y., 1994.

Please charge any fee necessary to enter this paper and any previous paper to deposit account 09-0468.

Respectfully submitted,

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